

Figure 1

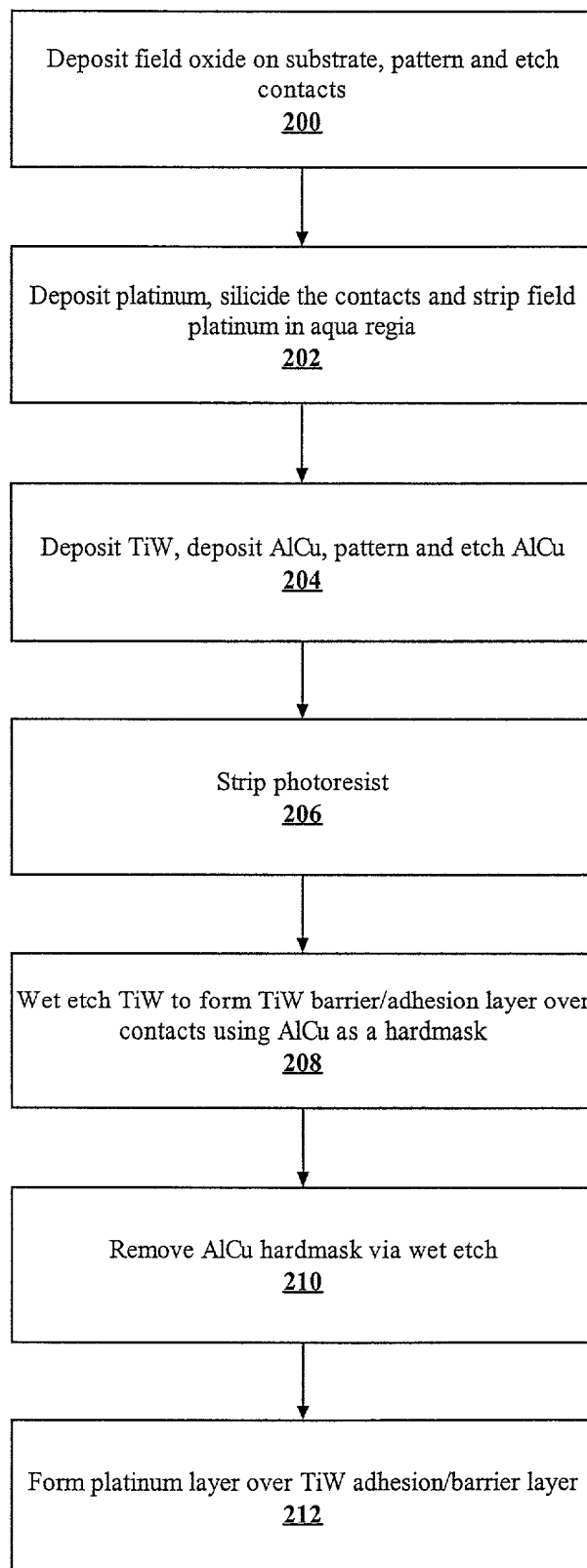


Figure 2

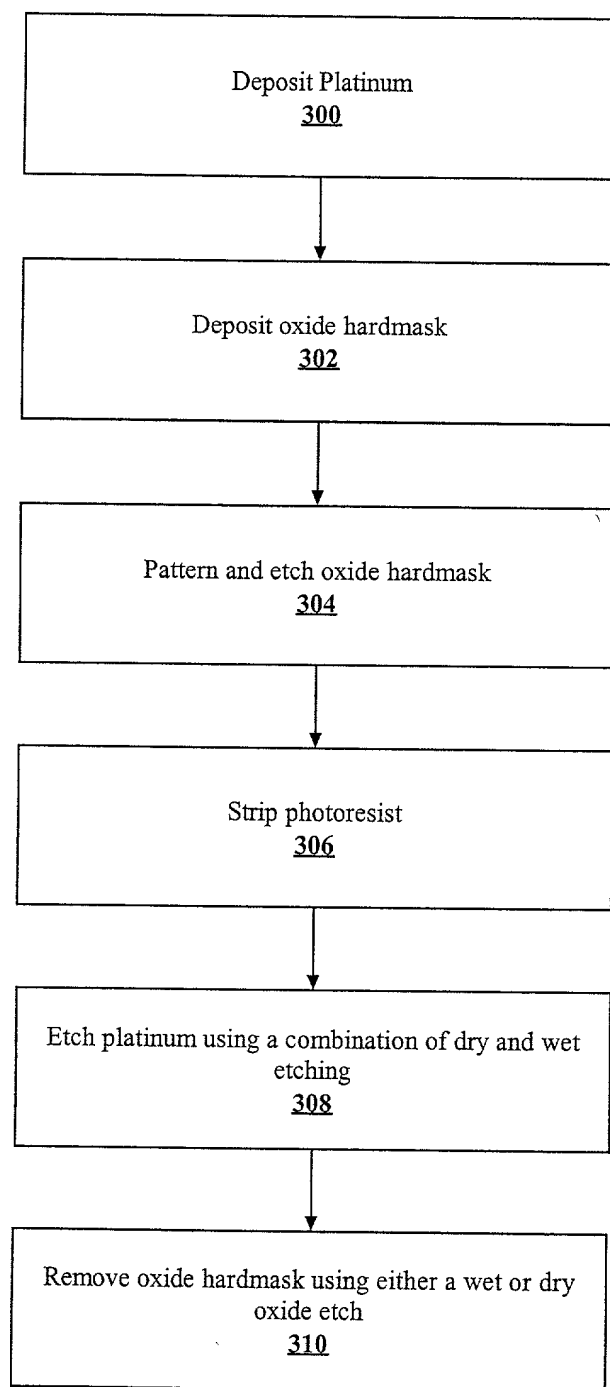


Figure 3

Pattern and etch contacts

Strip resist

Deposit Platinum and silicide the contacts

Strip field Pt in aqua regia

402
Field oxide

404
Pt_x-Si contact

401

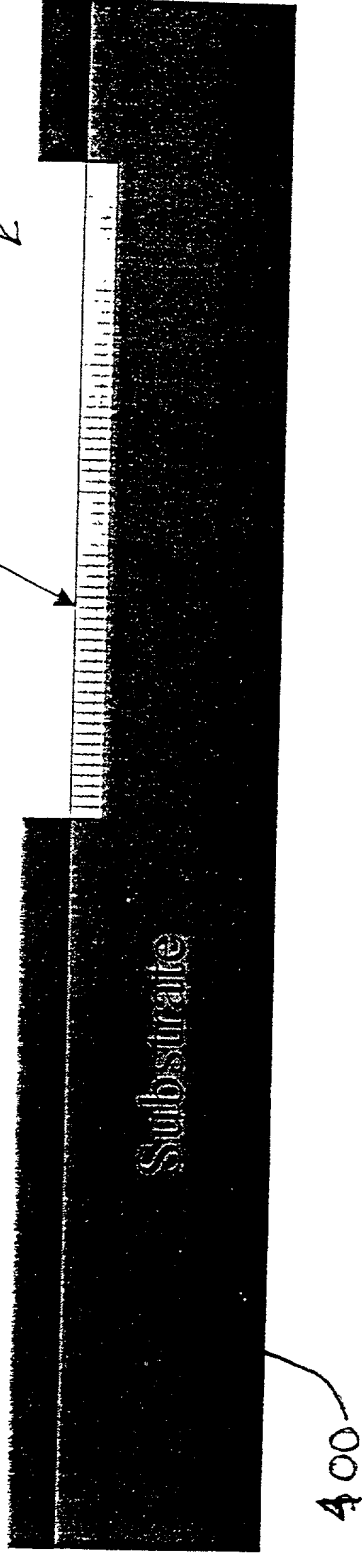


Figure 4a

Deposit TiW

Pattern and etch TiW barrier over contacts

Strip resist

406
TiW

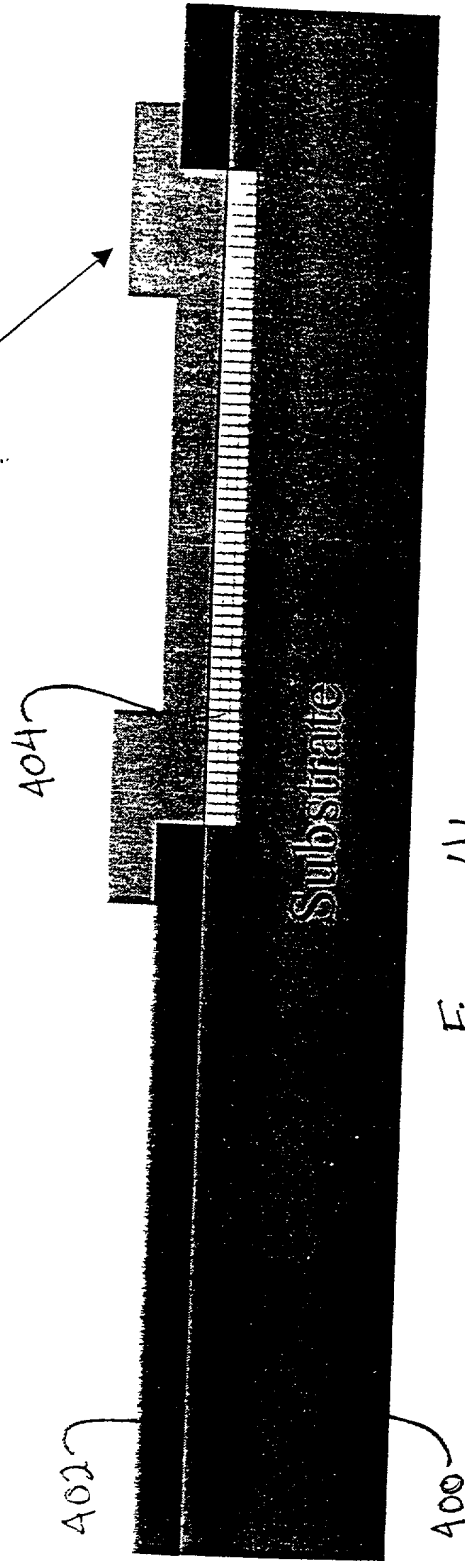


Figure 4b

Note: contingency field on reticle for TiW adhesion layer under all interconnect

Deposit Platinum for interconnect

Deposit oxide for hardmask

Pattern and etch hardmask

Strip resist

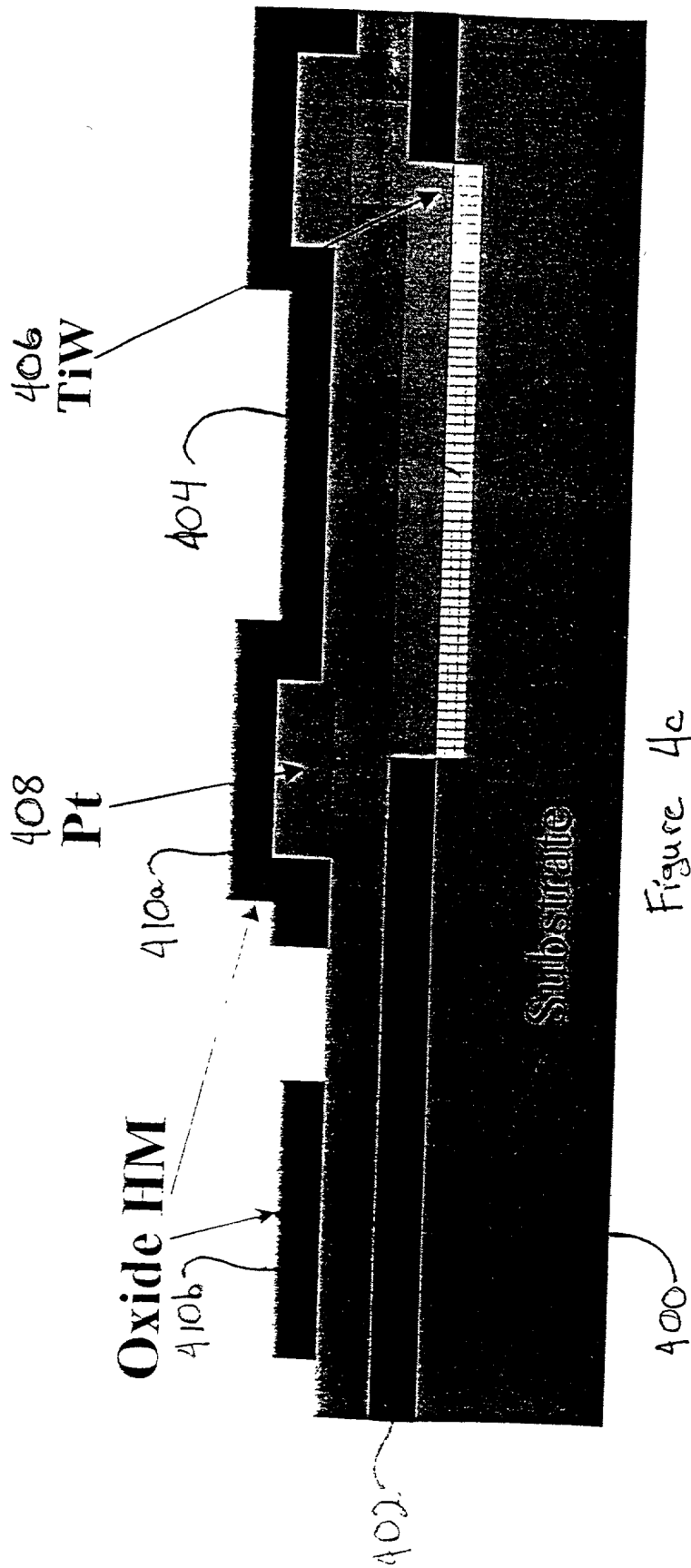


Figure 4c

Etch Platinum for interconnect

Remove hardmask

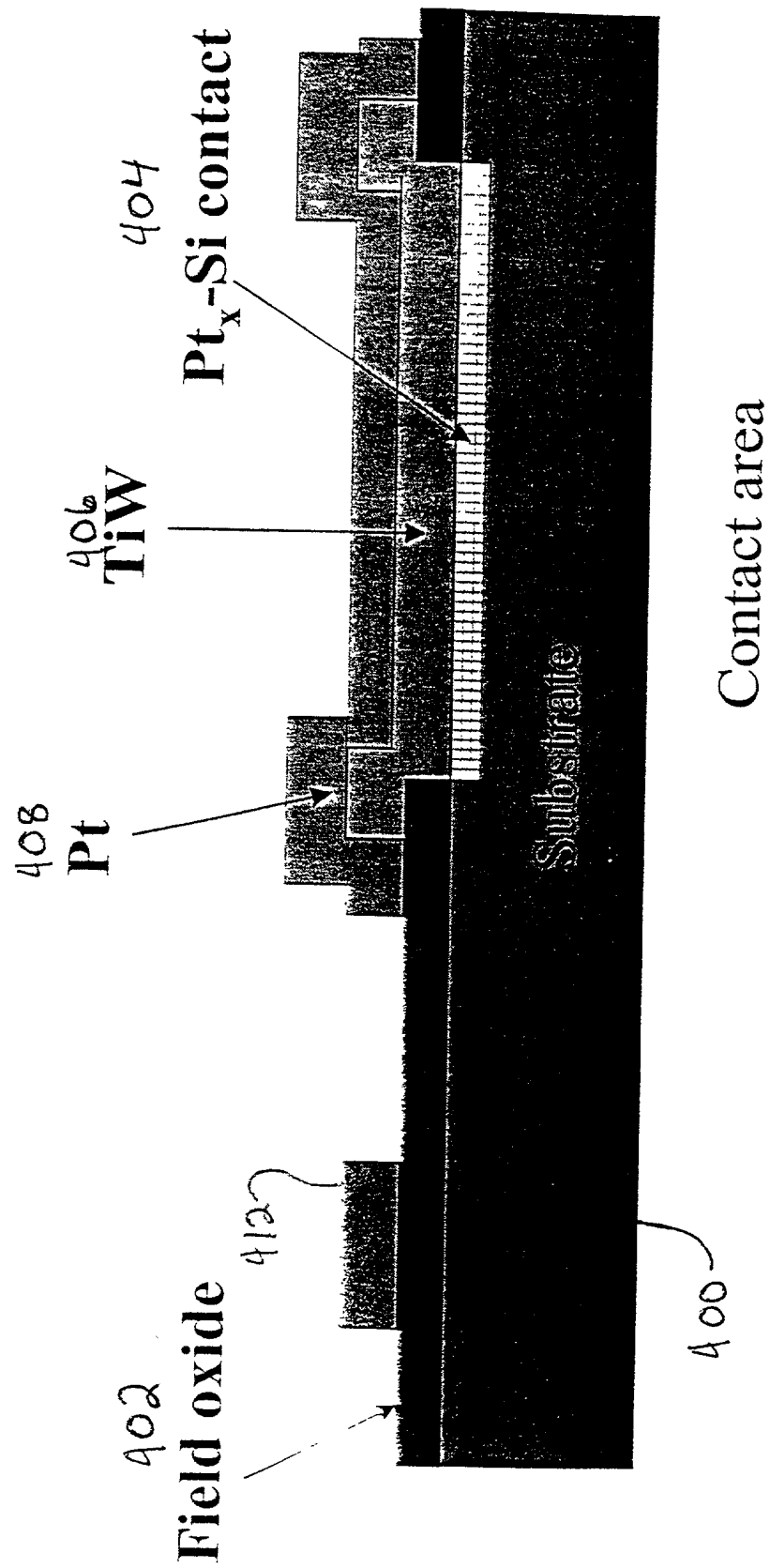


Figure 4d

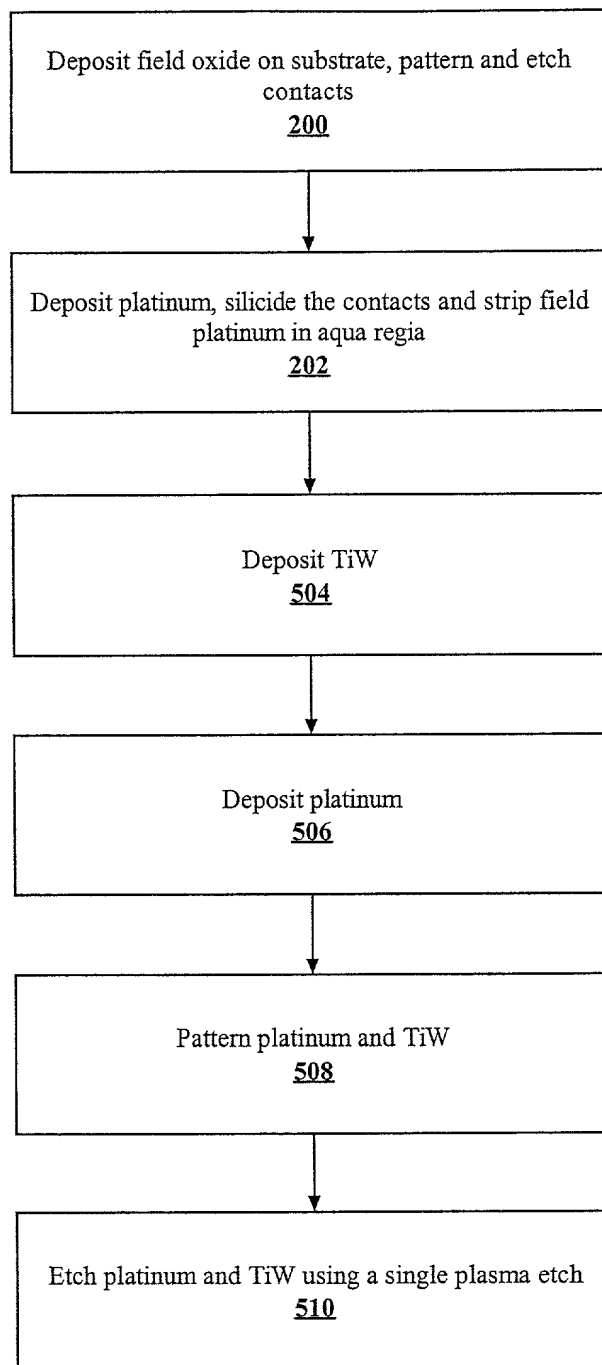


Figure 5

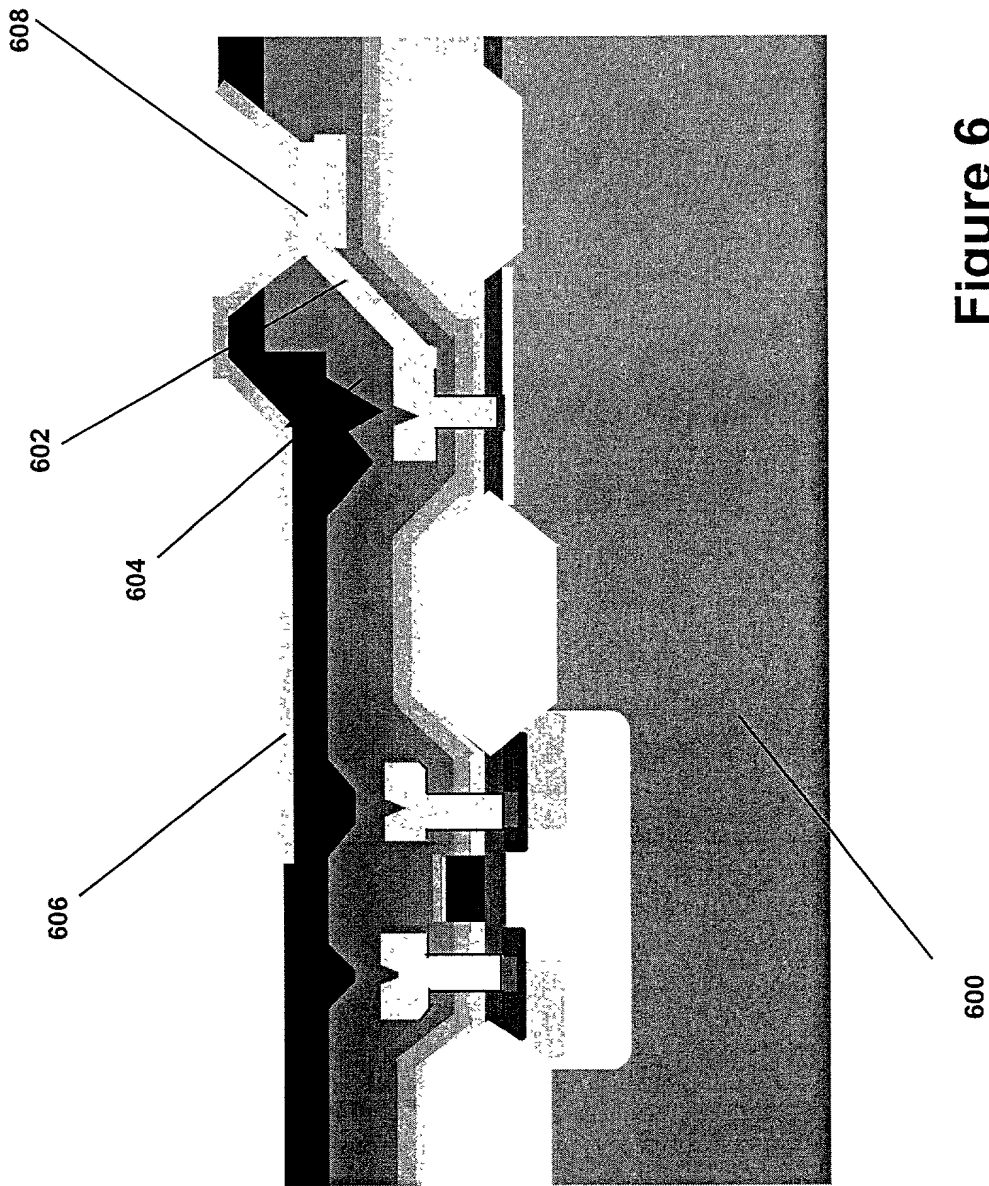


Figure 6